Product/Process Change Notice (PCN) Major change ☐ Minor change PCN #: PCN_FeCBF_20160322_Capacity_Increase ☐ Product Mark Date Code Product Affected: WE-CBF Packaging PCN Date: 01.05.2016 ○ Others Effective Date: 01.08.2016 Contact: Product Management Attachment: Yes ⊠ No Phone: +49 (0) 7942 - 945 5001 Samples: Fax: +49 (0) 7942 - 945 5179 E-mail: pcn.eisos@we-online.de **DESCRIPTION AND PURPOSE OF CHANGE:** In order to increase the production capability Würth Elektronik eiSos GmbH & Co. KG will implement another production line. There will be no change in form, fit, function, quality or reliability of the product. **DETAIL OF CHANGE:** The production lines can be identified by the first three digits of the lot number. 1. Lot No. of already established production line: Lot number starting with 187 Country of Origin: Taiwan Lot No. of additional production line: Lot number starting with 241 Country of Origin: Taiwan 2. Affected part numbers: Part number Size WE-CBF 742792311 1210 742792312

RELIABILITY / QUALIFICATION SUMMARY:

Process approval is according to internal requirements released by the Quality Department and the Product Management Department.

Please see the Reliability Overview as below. All Tests were passed

| | Test | Qty | Reference | Test conditions |
|----|---|------|---------------------------|--|
| 1 | High Temperature Exposure (Storage) | 0/30 | MIL-STD-202 Method 108 | Preconditioning: 1 time lead-free Heat exposure Temperature: 125±3°C* Testing time: 500h Unpowered. Measurement at 24±2 hours after test conclusion. |
| 2 | Moisture Resistance | 0/30 | MIL-STD-202 Method 106 | Preconditioning: 1 time lead-free Heat exposure Time/Cycle = 24 h; Temperature: 65±2°C 500h, Humidity: 95%, Unpowered. Measurement at 24±2 hours after test conclusion. |
| 3 | Operational Life | 0/30 | MIL-PRF-27 | Preconditioning: 1 time lead-free Heat exposure Testing time: 1000h Temperature: Ambient Temp. 85±5°C* + rated current = 125°C* Measurement at 24±2 hours after test conclusion. |
| 4 | Terminal Strength (SMD) | 0/30 | internal spec. | Preconditioning: Solder components on test board (lead-free) Apply an individual force for 60 seconds. Please refer the attached table in the description below. |
| 5 | Vibration | 0/30 | MIL-STD-202 Method 204 | Preconditioning: Solder components on test board (lead-free) 10g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 15-2000 Hz. |
| 6 | Five Time Reflow | 0/30 | J-STD-020D | Lead -free soldering profile: Peak temperature according to table 4.2 of the J-STD-020 |
| 7 | Solderability | 0/30 | JESD22-B102 | For both Leaded & SMD. Electrical Test not required. Magnification 50X. Conditions: SMD: a) Method B, Steam Aging 4 hrs @ 98% r.H.@ 245°C |
| 8 | Thermal Shock | 0/30 | MIL-STD-202 Method 107 | Preconditioning: 1 time lead-free Heat exposure Temperature: -40°C/+125°C* Dwell time is 30 minutes. Cycles: 300 Transfer time max. 20s. |
| 9 | Board Flex | 0/30 | AEC-Q200-005 | Preconditioning: Solder components on test board (lead-free) Appendix 2 Note: 2mm (Min) Sample size: 30 |
| 10 | Low Temperature Storage Life | 0/30 | JESD22-A119 | Preconditioning: 1 time lead-free Heat exposure Temperature: -55±3°C Testing time: 500h Measurement at 24±2 hours after test conclusion. |

Note: *Use max. or min. temperatures according Würth Elektronik data sheet (current version) 30 pcs of each DUT (Device Under Test)

DATA SHEET CHANGE:

Yes

No